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Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	Preface; Contents; 1. Introduction; 2. History of Electromigration; 3. Experimental Studies of Al Interconnections; 4. Experimental Studies of Cu Interconnections; 5. Numerical Modeling of Electromigration; 6. Future Challenges; Index; Biography
Sommario/riassunto	""Electromigration in ULSI Interconnections"" provides a comprehensive description of the electro migration in integrated circuits. It is intended for both beginner and advanced readers on electro migration in ULSI interconnections. It begins with the basic knowledge required for a detailed study on electro migration, and examines the various interconnected systems and their evolution employed in integrated circuit technology. The subsequent chapters provide a detailed description of the physics of electro migration in both Al- and Cu- based Interconnections, in the form of theoretical, experim